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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

### Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	2MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	12
Program Memory Size	768B (512 x 12)
Program Memory Type	ОТР
EEPROM Size	-
RAM Size	25 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 3.8V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	18-DIP (0.300", 7.62mm)
Supplier Device Package	18-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lv54a-02i-p

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Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

# TABLE 1-1: PIC16C5X FAMILY OF DEVICES

Features	PIC16C54	PIC16CR54	PIC16C55	PIC16C56	PIC16CR56
Maximum Operation Frequency	40 MHz	20 MHz	40 MHz	40 MHz	20 MHz
EPROM Program Memory (x12 words)	512	_	512	1K	
ROM Program Memory (x12 words)		512	_	_	1K
RAM Data Memory (bytes)	25	25	24	25	25
Timer Module(s)	TMR0	TMR0	TMR0	TMR0	TMR0
I/O Pins	12	12	20	12	12
Number of Instructions	33	33	33	33	33
Packages	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP	28-pin DIP, SOIC; 28-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP

PIC16C58 Features **PIC16C57** PIC16CR57 PIC16CR58 Maximum Operation Frequency 20 MHz 40 MHz 40 MHz 20 MHz EPROM Program Memory (x12 words) 2K 2K \_\_\_\_ \_ ROM Program Memory (x12 words) 2K 2K \_ \_ RAM Data Memory (bytes) 72 72 73 73 Timer Module(s) TMR0 TMR0 TMR0 TMR0 I/O Pins 20 20 12 12 Number of Instructions 33 33 33 33 28-pin DIP, SOIC; 28-pin DIP, SOIC; 18-pin DIP, SOIC; 18-pin DIP, SOIC; Packages 28-pin SSOP 28-pin SSOP 20-pin SSOP 20-pin SSOP All PIC® Family devices have Power-on Reset, selectable Watchdog Timer, selectable Code Protect and high I/O current capability.

# 3.0 ARCHITECTURAL OVERVIEW

The high performance of the PIC16C5X family can be attributed to a number of architectural features commonly found in RISC microprocessors. To begin with, the PIC16C5X uses a Harvard architecture in which program and data are accessed on separate buses. This improves bandwidth over traditional von Neumann architecture where program and data are fetched on the same bus. Separating program and data memory further allows instructions to be sized differently than the 8-bit wide data word. Instruction opcodes are 12 bits wide making it possible to have all single word instructions. A 12-bit wide program memory access bus fetches a 12-bit instruction in a single cycle. A twostage pipeline overlaps fetch and execution of instructions. Consequently, all instructions (33) execute in a single cycle except for program branches.

The PIC16C54/CR54 and PIC16C55 address 512 x 12 of program memory, the PIC16C56/CR56 address 1K x 12 of program memory, and the PIC16C57/CR57 and PIC16C58/CR58 address 2K x 12 of program memory. All program memory is internal.

The PIC16C5X can directly or indirectly address its register files and data memory. All special function registers including the program counter are mapped in the data memory. The PIC16C5X has a highly orthogonal (symmetrical) instruction set that makes it possible to carry out any operation on any register using any addressing mode. This symmetrical nature and lack of 'special optimal situations' make programming with the PIC16C5X simple yet efficient. In addition, the learning curve is reduced significantly. The PIC16C5X device contains an 8-bit ALU and working register. The ALU is a general purpose arithmetic unit. It performs arithmetic and Boolean functions between data in the working register and any register file.

The ALU is 8 bits wide and capable of addition, subtraction, shift and logical operations. Unless otherwise mentioned, arithmetic operations are two's complement in nature. In two-operand instructions, typically one operand is the W (working) register. The other operand is either a file register or an immediate constant. In single operand instructions, the operand is either the W register or a file register.

The W register is an 8-bit working register used for ALU operations. It is not an addressable register.

Depending on the instruction executed, the ALU may affect the values of the Carry (C), Digit Carry (DC), and Zero (Z) bits in the STATUS register. The C and DC bits operate as a borrow and digit borrow out bit, respectively, in subtraction. See the SUBWF and ADDWF instructions for examples.

A simplified block diagram is shown in Figure 3-1, with the corresponding device pins described in Table 3-1 (for PIC16C54/56/58) and Table 3-2 (for PIC16C55/57).



## FIGURE 3-1: PIC16C5X SERIES BLOCK DIAGRAM

# 5.2 Device Reset Timer (DRT)

The Device Reset Timer (DRT) provides an 18 ms nominal time-out on RESET regardless of Oscillator mode used. The DRT operates on an internal RC oscillator. The processor is kept in RESET as long as the DRT is active. The DRT delay allows VDD to rise above VDD min., and for the oscillator to stabilize.

Oscillator circuits based on crystals or ceramic resonators require a certain time after power-up to establish a stable oscillation. The on-chip DRT keeps the device in a RESET condition for approximately 18 ms after the voltage on the MCLR/VPP pin has reached a logic high (VIH) level. Thus, external RC networks connected to the MCLR input are not required in most cases, allowing for savings in cost-sensitive and/or space restricted applications.

The Device Reset time delay will vary from chip to chip due to VDD, temperature, and process variation. See AC parameters for details.

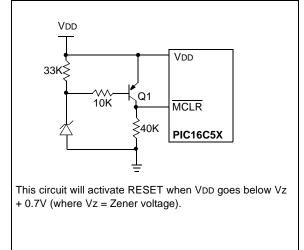
The DRT will also be triggered upon a Watchdog Timer time-out. This is particularly important for applications using the WDT to wake the PIC16C5X from SLEEP mode automatically.

# 5.3 Reset on Brown-Out

A brown-out is a condition where device power (VDD) dips below its minimum value, but not to zero, and then recovers. The device should be RESET in the event of a brown-out.

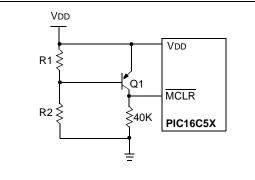
To RESET PIC16C5X devices when a brown-out occurs, external brown-out protection circuits may be built, as shown in Figure 5-6, Figure 5-7 and Figure 5-8.





## FIGURE 5-7:

### EXTERNAL BROWN-OUT PROTECTION CIRCUIT 2

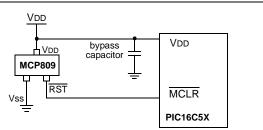


This brown-out circuit is less expensive, although less accurate. Transistor Q1 turns off when VDD is below a certain level such that:

$$V_{DD} \bullet \frac{R1}{R1 + R2} = 0.7V$$

### FIGURE 5-8:

### EXTERNAL BROWN-OUT PROTECTION CIRCUIT 3



This brown-out protection circuit employs Microchip Technology's MCP809 microcontroller supervisor. The MCP8XX and MCP1XX families of supervisors provide push-pull and open collector outputs with both "active high and active low" RESET pins. There are 7 different trip point selections to accommodate 5V and 3V systems.

## 6.4 **OPTION Register**

The OPTION Register is a 6-bit wide, write-only register which contains various control bits to configure the Timer0/WDT prescaler and Timer0.

By executing the OPTION instruction, the contents of the W Register will be transferred to the OPTION Register. A RESET sets the OPTION<5:0> bits.

## **REGISTER 6-2: OPTION REGISTER**

U-0	U-0	W-1	W-1	W-1	W-1	W-1	W-1
_	_	TOCS	TOSE	PSA	PS2	PS1	PS0
bit 7							bit 0

- bit 7-6: Unimplemented: Read as '0'
- bit 5: **TOCS**: Timer0 clock source select bit
  - 1 = Transition on T0CKI pin
  - 0 = Internal instruction cycle clock (CLKOUT)
- bit 4: **TOSE**: Timer0 source edge select bit
  - 1 = Increment on high-to-low transition on T0CKI pin
  - 0 = Increment on low-to-high transition on T0CKI pin
- bit 3: **PSA**: Prescaler assignment bit
  - 1 = Prescaler assigned to the WDT
  - 0 = Prescaler assigned to Timer0

### bit 2-0: **PS<2:0>:** Prescaler rate select bits

Bit Value	Timer0 Rate	WDT Rate
000	1:2	1:1
001	1:4	1:2
010	1:8	1:4
011	1:16	1:8
100	1:32	1:16
101	1:64	1:32
110	1 : 128	1:64
111	1:256	1:128

Legend:				
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'		
-n = Value at POR	1 = bit is set	0 = bit is cleared	x = bit is unknown	





# FIGURE 8-4: TIMER0 TIMING: INTERNAL CLOCK/PRESCALER 1:2



### TABLE 8-1: REGISTERS ASSOCIATED WITH TIMER0

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on Power-on Reset	<u>Value</u> on MCLR and WDT Reset
01h	TMR0	TMR0 Timer0 - 8-bit real-time clock/counter						xxxx xxxx	uuuu uuuu		
N/A	OPTION	_		TOCS	TOSE	PSA	PS2	PS1	PS0	11 1111	11 1111

Legend: x = unknown, u = unchanged, - = unimplemented. Shaded cells not used by Timer0.

#### CONFIGURATION WORD FOR PIC16C54/C55/C56/C57 **REGISTER 9-2:**

							İ	СР	WDTE	FOSC1	FOSC0
		_	_	_				CP	WDIE	FUSCI	
bit 11											bit 0
bit 11-4:	Unimple	mented	Read as '	0'							
bit 3:	CP: Cod	e protecti	on bit.								
		e protecti									
	0 = Code	e protectio	on on								
bit 2:	WDTE: \	Vatchdog	timer ena	ble bit							
	1 = WDT	enabled									
	0 = WDT	disabled									
bit 1-0:	FOSC1:I	FOSC0: (	Oscillator s	election b	oits <sup>(2)</sup>						
	00 = LF	oscillato	or								
	01 = X	T oscillato	or								
		S oscillato									
	11 = R	C oscillate	or								
Note 1.	Refer to t	ha PIC16	C5X Prog	rammina	Specificat	ions (Liter	atura Num	her DS3	190) to d	otormino l	now to
			iration wor	0	opeemear				, 100) to u		1011 10
2:		•	orts XT, R		oscillator	onlv.					
						- 1					
Legend:											

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, re	ead as '0'
-n = Value at POR	1 = bit is set	0 = bit is cleared	x = bit is unknown

NOTES:

ADDWF	Add W	and f			
Syntax:	[ label ] A	DDWF	f,d		
Operands:	$\begin{array}{l} 0 \leq f \leq 31 \\ d \in [0,1] \end{array}$				
Operation:	(W) + (f)	$\rightarrow$ (dest)			
Status Affected:	C, DC, Z				
Encoding:	0001	11df	ffff		
Description:	Add the contents of the W register and register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is '1' the result is stored back in register 'f'.				
Words:	1				
Cycles:	1				
Example:	ADDWF	TEMP_RE	G, 0		
Before Instr W TEMP_I After Instruc W TEMP_F	= REG = ction =	0x17 0xC2 0xD9 0xC2			

ANDWF	AND W with f
Syntax:	[label] ANDWF f,d
Operands:	$\begin{array}{l} 0 \leq f \leq 31 \\ d \in [0,1] \end{array}$
Operation:	(W) .AND. (f) $\rightarrow$ (dest)
Status Affected:	Z
Encoding:	0001 01df ffff
Description:	The contents of the W register are AND'ed with register 'f'. If 'd' is 0 the result is stored in the W regis- ter. If 'd' is '1' the result is stored back in register 'f'.
Words:	1
Cycles:	1
Example:	ANDWF TEMP_REG, 1
Before Instru W TEMP_ After Instruc W TEMP_	= 0x17 REG = 0xC2 tion = 0x17

ANDLW	AND literal with W				
Syntax:	[ <i>label</i> ] ANDLW k				
Operands:	$0 \le k \le 255$				
Operation:	(W).AND. (k) $\rightarrow$ (W)				
Status Affected:	Z				
Encoding:	1110 kkkk kkkk				
Description:	The contents of the W register are AND'ed with the eight-bit literal 'k'. The result is placed in the W regis- ter.				
Words:	1				
Cycles:	1				
Example:	ANDLW H'5F'				
Before Instruction W = 0xA3 After Instruction W = 0x03					

BCF	Bit Clea	r f				
Syntax:	[ label ]	[label] BCF f,b				
Operands:	$\begin{array}{l} 0 \leq f \leq 3^{\prime} \\ 0 \leq b \leq 7 \end{array}$	-				
Operation:	$0 \rightarrow (f < b$	>)				
Status Affected:	None					
Encoding:	0100	bbbf	ffff			
Description:	Bit 'b' in	register 'f'	is cleared.			
Words:	1					
Cycles:	1					
Example:	BCF	FLAG_RE	IG, 7			
Before Instruction FLAG_REG = 0xC7 After Instruction						
FLAG_F	REG =	0x47				

NOTES:

## **13.6** Timing Diagrams and Specifications



## FIGURE 13-2: EXTERNAL CLOCK TIMING - PIC16CR54A

## TABLE 13-1: EXTERNAL CLOCK TIMING REQUIREMENTS - PIC16CR54A

AC Characteristics		$\begin{array}{ll} \mbox{Standard Operating Conditions (unless otherwise specified)} \\ \mbox{Operating Temperature} & 0^{\circ}C \leq TA \leq +70^{\circ}C \ \ for \ commercial \\ -40^{\circ}C \leq TA \leq +85^{\circ}C \ \ for \ industrial \\ -40^{\circ}C \leq TA \leq +125^{\circ}C \ \ for \ extended \end{array}$								
Param No.	Symbol	Characteristic		Min Typ†		Units	Conditions			
	Fosc	External CLKIN Frequency <sup>(1)</sup>	DC	_	4.0	MHz	XT OSC mode			
			DC	—	4.0	MHz	HS osc mode (04)			
			DC	_	10	MHz	HS osc mode (10)			
			DC	—	20	MHz	HS osc mode (20)			
			DC	_	200	kHz	LP osc mode			
		Oscillator Frequency <sup>(1)</sup>	DC		4.0	MHz	RC OSC mode			
			0.1	_	4.0	MHz	XT osc mode			
			4.0	_	4.0	MHz	HS osc mode (04)			
			4.0	_	10	MHz	HS osc mode (10)			
			4.0	_	20	MHz	HS osc mode (20)			
			5.0	—	200	kHz	LP osc mode			

\* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.

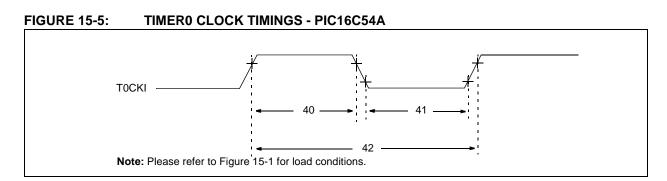
**2:** Instruction cycle period (TCY) equals four times the input oscillator time base period.

## 15.3 DC Characteristics: PIC16LV54A-02 (Commercial) PIC16LV54A-02I (Industrial)

PIC16LV54A-02 PIC16LV54A-02I (Commercial, Industrial)				$\begin{array}{ll} \mbox{Standard Operating Conditions (unless otherwise specified)} \\ \mbox{Operating Temperature} & 0^{\circ}C \leq TA \leq +70^{\circ}C \mbox{ for commercial} \\ -20^{\circ}C \leq TA \leq +85^{\circ}C \mbox{ for industrial} \end{array}$					
Param No.	Symbol	Characteristic	Min Typ† N		Max	Units	Conditions		
D001	Vdd	Supply Voltage RC and XT modes	2.0	_	3.8	V			
D002	Vdr	RAM Data Retention Voltage <sup>(1)</sup>	—	1.5*	—	V	Device in SLEEP mode		
D003	VPOR	VDD Start Voltage to ensure Power-on Reset	—	Vss	—	V	See Section 5.1 for details on Power-on Reset		
D004	SVDD	VDD Rise Rate to ensure Power-on Reset	0.05*		—	V/ms	See Section 5.1 for details on Power-on Reset		
D010	IDD	<b>Supply Current<sup>(2)</sup></b> RC <sup>(3)</sup> and XT modes LP mode, Commercial LP mode, Industrial		0.5 11 14	 27 35	μA	Fosc = 2.0 MHz, VDD = 3.0V Fosc = 32 kHz, VDD = 2.5V WDT disabled Fosc = 32 kHz, VDD = 2.5V WDT disabled		
D020	IPD	<b>Power-down Current<sup>(2,4)</sup></b> Commercial Commercial Industrial Industrial		2.5 0.25 3.5 0.3	12 4.0 14 5.0	μΑ μΑ μΑ μΑ	VDD = 2.5V, WDT enabled VDD = 2.5V, WDT disabled VDD = 2.5V, WDT enabled VDD = 2.5V, WDT disabled		

These parameters are characterized but not tested.

- † Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.
- **Note 1:** This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.
  - 2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.
    - a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to VSS, T0CKI = VDD, MCLR = VDD; WDT enabled/ disabled as specified.
    - b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.
  - **3:** Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in kΩ.
  - 4: The oscillator start-up time can be as much as 8 seconds for XT and LP oscillator selection on wake-up from SLEEP mode or during initial power-up.



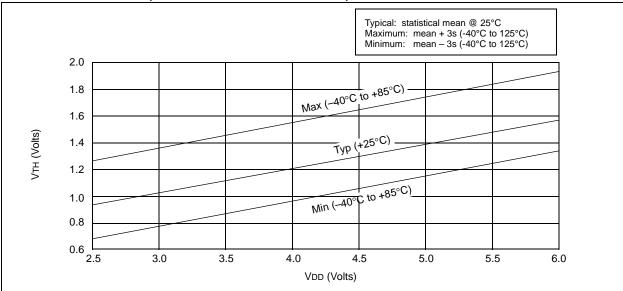
# TABLE 15-4: TIMER0 CLOCK REQUIREMENTS - PIC16C54A

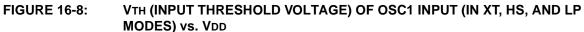
		Standard Operating	g Conditions (ur	nless o	therw	ise spe	ecified)				
		Operating Temperat	ture $0^{\circ}C \le TA \le +70^{\circ}C$ for commercial								
1	AC Chara	octeristics	$-40^{\circ}C \le$	$-40^{\circ}C \le TA \le +85^{\circ}C$ for industrial							
			$-20^{\circ}C \le$	TA ≤ +8	85°C fc	or indus	trial - PIC16LV54A-02I				
			$-40^{\circ}C \le$	Ta ≤ +1	25°C	for exte	nded				
Param No.	Symbol	Characteristic	Min	Тур†	Max	Units	Conditions				
40	Tt0H	T0CKI High Pulse Width									
		- No Prescaler	0.5 TCY + 20*	—	—	ns					
		- With Prescaler	10*	—	_	ns					
41	Tt0L	T0CKI Low Pulse Width									
		- No Prescaler	0.5 TCY + 20*	—	—	ns					
		- With Prescaler	10*	—	_	ns					
42	Tt0P	T0CKI Period	20 or <u>TCY + 40</u> *	—	_	ns	Whichever is greater.				
			N				N = Prescale Value				
							(1, 2, 4,, 256)				

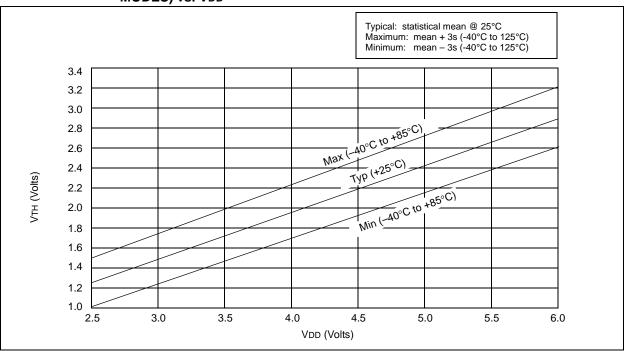
\* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 16-7: VTH (INPUT THRESHOLD VOLTAGE) OF I/O PINS - VDD





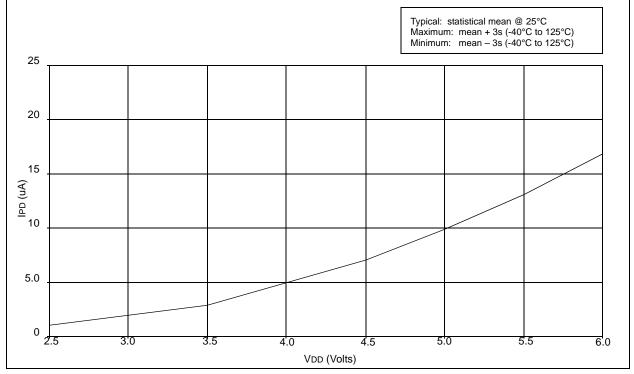




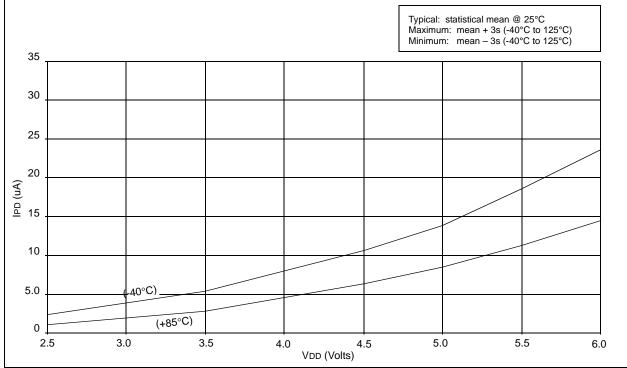
## FIGURE 16-17: TRANSCONDUCTANCE (gm) OF HS OSCILLATOR vs. VDD













### FIGURE 19-5: RESET, WATCHDOG TIMER, AND DEVICE RESET TIMER TIMING - PIC16C5X-40

## TABLE 19-3: RESET, WATCHDOG TIMER, AND DEVICE RESET TIMER - PIC16C5X-40

AC Characteristics		Standard Operating Conditions (unless otherwise specified)Operating Temperature $0^{\circ}C \le TA \le +70^{\circ}C$ (commercial)Operating Voltage VDD range is described in Section 19.1.								
Param No.	Symbol	Characteristic	Min	Тур†	† Max U		Conditions			
30	TmcL	MCLR Pulse Width (low)		_	_	ns	VDD = 5.0V			
31	Twdt	Watchdog Timer Time-out Period (No Prescaler)	9.0*	18*	30*	ms	VDD = 5.0V (Comm)			
32	Tdrt	Device Reset Timer Period	9.0*	18*	30*	ms	VDD = 5.0V (Comm)			
34	Tioz	I/O Hi-impedance from MCLR Low	100*	300*	1000*	ns				

\* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

# 28-Lead Plastic Dual In-line (P) - 600 mil (PDIP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units		INCHES*		N	1ILLIMETERS	6
Dimer	ision Limits	MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		28			28	
Pitch	р		.100			2.54	
Top to Seating Plane	А	.160	.175	.190	4.06	4.45	4.83
Molded Package Thickness	A2	.140	.150	.160	3.56	3.81	4.06
Base to Seating Plane	A1	.015			0.38		
Shoulder to Shoulder Width	E	.595	.600	.625	15.11	15.24	15.88
Molded Package Width	E1	.505	.545	.560	12.83	13.84	14.22
Overall Length	D	1.395	1.430	1.465	35.43	36.32	37.21
Tip to Seating Plane	L	.120	.130	.135	3.05	3.30	3.43
Lead Thickness	С	.008	.012	.015	0.20	0.29	0.38
Upper Lead Width	B1	.030	.050	.070	0.76	1.27	1.78
Lower Lead Width	В	.014	.018	.022	0.36	0.46	0.56
Overall Row Spacing	§ eB	.620	.650	.680	15.75	16.51	17.27
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	5	10	15	5	10	15	

\* Controlling Parameter § Significant Characteristic

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MO-011 Drawing No. C04-079

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2.	How does this document meet your hard	ware and software development needs?
3.	Do you find the organization of this data s	sheet easy to follow? If not, why?
4.	What additions to the data sheet do you t	hink would enhance the structure and subject?
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5.	What deletions from the data sheet could	be made without affecting the overall usefulness?
6	Is there any incorrect or misleading inform	nation (what and where)?
0.		
7.	How would you improve this document?	
8.	How would you improve our software, sys	stems, and silicon products?